EIGHTEENTH ANNUAL

BiTS™

Burn-in & Test Strategies Workshop

March 5 - 8, 2017

Hilton Phoenix / Mesa Hotel
Mesa, Arizona

Archive - Closing

Summary

Learn…

- Tutorial, Keynote, 32 Papers, 19 Posters

  > 900 PowerPoint slides

Explore…

- BiTS EXPO: 52

Share…

- Meals, Networking, Social Event

What's *NOW & NEXT* in Test & Burn-in of Packaged ICs

THE BITS

SPEAKEASY

EST. 2017

TUESDAY 6:30 – 9:30 PM

BE SURE TO GET THE SECRET LOCATION & PASSPHRASE!
(ASK A COMMITTEE MEMER OR THE BITS DESK)

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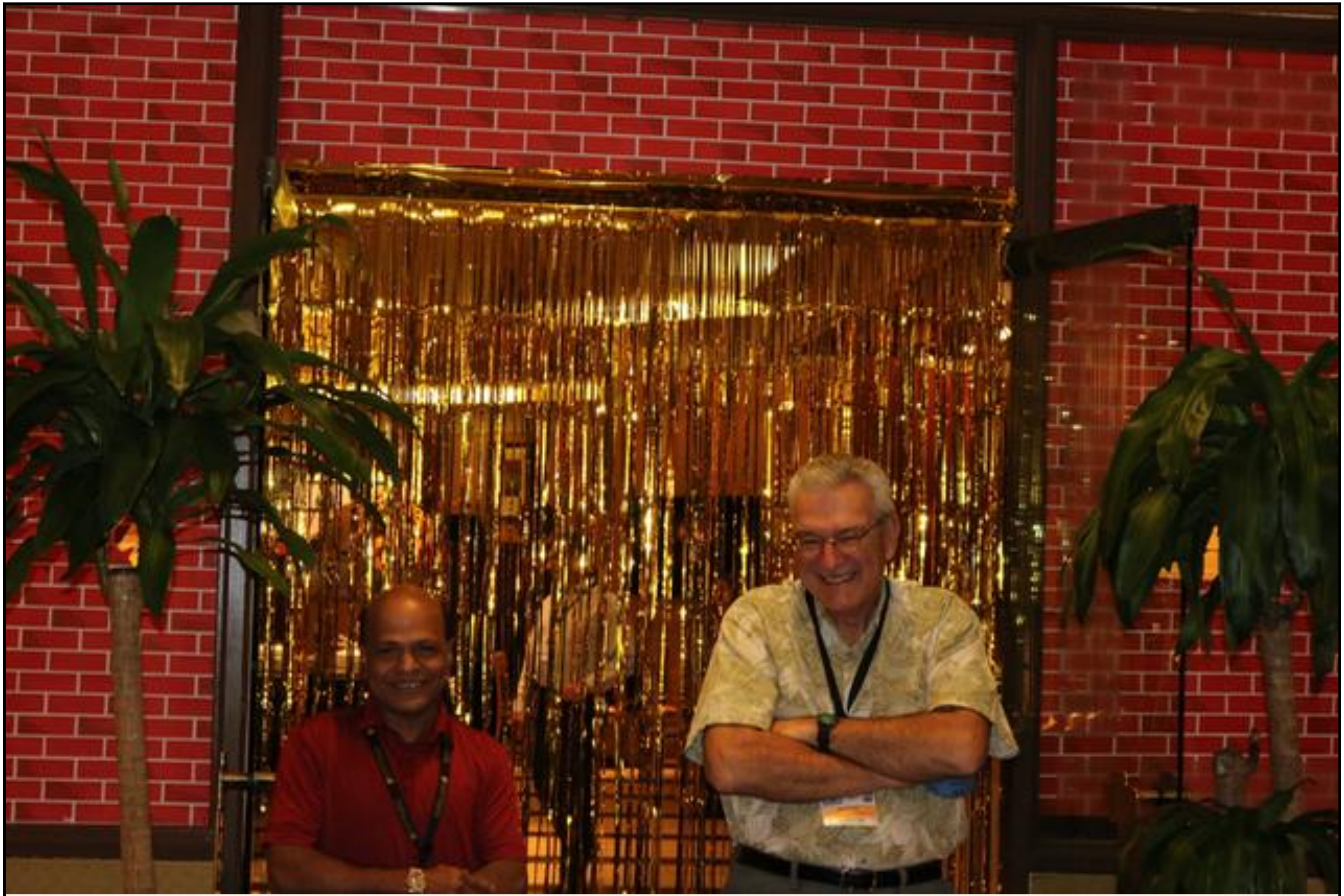

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Archive - Closing

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David Pfaff
Takuya Kojima

Bill Walkowski
Carol McCuen

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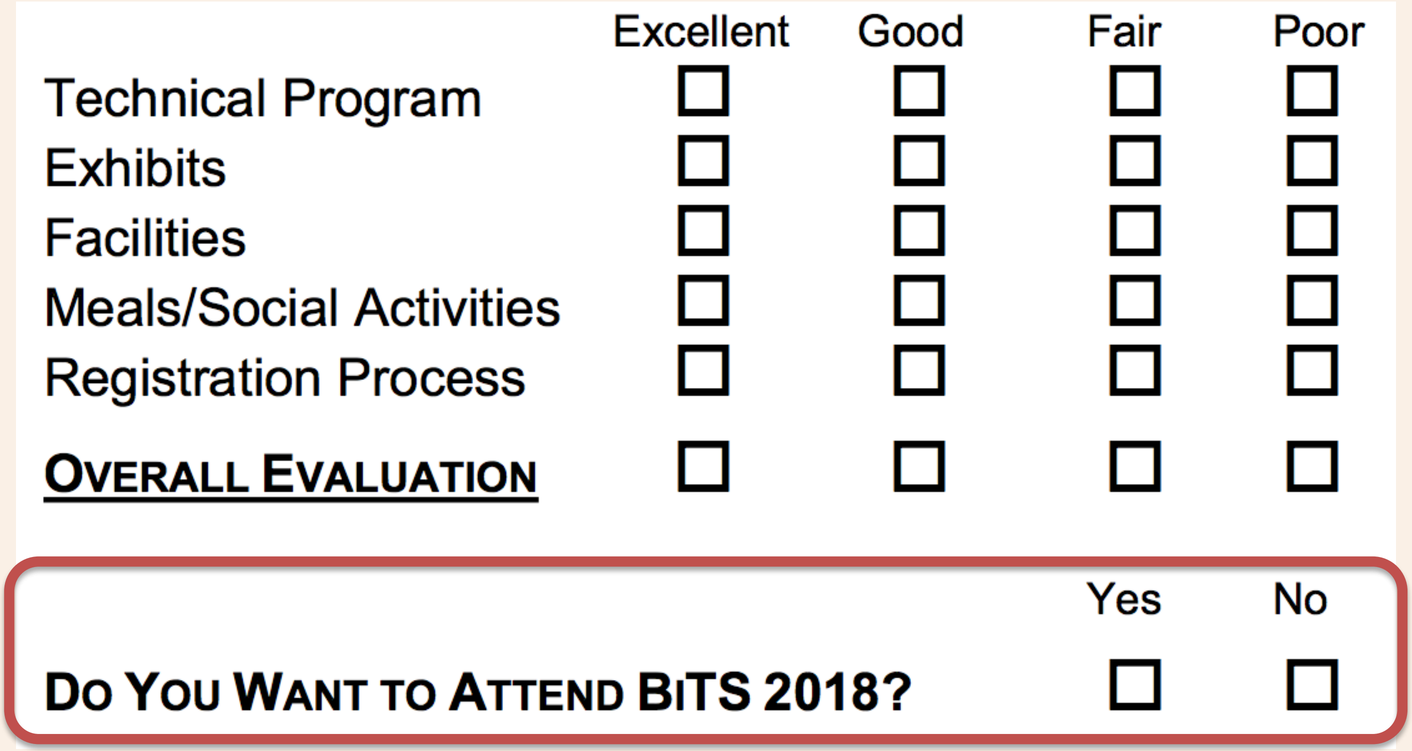
Yoshida-san, Krishna Mohan, Nadia Steckler, Bill Walkowski

Steve Durrett

Have the LAST WORD!



	Excellent	Good	Fair	Poor
Technical Program	☐	☐	☐	☐
Exhibits	☐	☐	☐	☐
Facilities	☐	☐	☐	☐
Meals/Social Activities	☐	☐	☐	☐
Registration Process	☐	☐	☐	☐
Overall Evaluation	☐	☐	☐	☐

	Yes	No
Do You Want to Attend BiTS 2018?	☐	☐

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Your Complete Source For Information About BiTS

Current Workshop

- Call For Papers
- EXPO & Sponsorships
- Advance/Final Program
- Registration Information & Forms; Register On-line
- Author Information
- Hotel Information/Travel

Features

- Committee Members
- Contact BiTS - Add to Mailing List & Inquiries
- Links to Other Websites
- ‘Press’ About BiTS
- Archive of past BiTS
- Search BiTS Feature

Plus Premium Archive…

BiTS Premium Archive

Updated Shortly!

- Multimedia
  - Audio with synchronized slides & pointer
  - BiTS 2014 - 2016 & BiTS China 2015 - 2016
  - BiTS 2017 posted shortly after BiTS
- Additional content
  - Tutorials
- Subscription Model
  - BiTS 2017 Professional Attendees – Subscription for One Year
  - Subscriber – Nominal Fee
    - Applied to BiTS 2018 Registration

bitsworkshop.org/premium

BiTS 2017 Early Bird Abstracts

Author(s)	Company
Noureen Sajid & Jeff Sherry	Johnstech International
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Justin Yun, BoHyun Kim & Dave Oh	TSE Co,.Ltd
Thiha Shwe, Hisashi Ata & Kenichi Sato	Texas Instruments / Yokowo
James Tong	Texas Instruments
Yuanjun Shi	TwinSolution Technology Ltd
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THANK YOU EXHIBITORS!

EXPO 2017

Exhibitors & Booth Assignments

Aehr Test Systems	A28
Aries Electronics, Inc.	A25
Astronics Test Systems	A18
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CMR Summit	A9
Cohu ITS	A3
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KYEC USA	A37
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Micro Control Company	A5
MicroConnex	K5
Microfriend	A11
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R&D Altanova	A1
Rika Denshi	A23
Rosenberger	K4
Sensata Technologies	A34, A35
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TDK-Lambda Americas	A10
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TSE Co,. Ltd	A13
Tokyo Electron Limited	K3
TwinSolution Technology Ltd	A27
WinWay Technology	A17
Xcerra - Multitest	A31
Yamaichi Electronics USA, Inc.	A47

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Call for BiTS 2018

March 4-7, 2018 ◆ Mesa, Arizona

Presentations ◆ Posters ◆ Tutorial

Share your latest work and advancements as an **AUTHOR**! Your presentation or poster will be part of a stimulating and comprehensive program. Explore a demanding topic as a **TUTORIAL INSTRUCTOR**. Share your expertise with participants eager to build their leading edge skills. Presentation, Poster & Tutorial proposals addressing a broad range of burn-in and test subjects are welcome, including, but not limited to:

- Socketing/Contacting of Contemporary and Advanced Packaging Technologies
- PCBs, Materials, Handlers, Contact
- Technologies, Burn-in Tooling
- Modeling, Characterization & Analysis
- Process & Operational Challenges
- WLCSP Test for KGD or Final Test
- MEMS and Non-Electrical Stimuli Test

BiTS EXPO 2018 & Sponsors

The EVENT for exhibiting your company's products & services. Showcase and promote what is ***Now & Next!***

Don't miss out! See the registration desk to sign up now at the early-bird discount rate. **BiTS EXPO** is sure to sell out!

For more information about BiTS 2018
please contact the BITS Office
bitsinfo@bitsworkshop.org

Submissions now open
abstracts2018@bitsworkshop.org

BiTS "Special" Award

For the Least Concealed Sales Pitch

(Almost)
Brilliant
Disguise

"Semi-retired" but always available…

BiTS Awards

- Best Presentation
- Best Poster
- Best Data Presented
- Most Inspirational Presentation
- Most Educational (Tutorial in Nature)
- Attendee Choice
    - Announced post-event

BiTS CHINA 中国

Shanghai

week of September 4, 2017

(exact date to be confirmed)

BiTS 2018

BiTS™

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March 4 – 7, 2018

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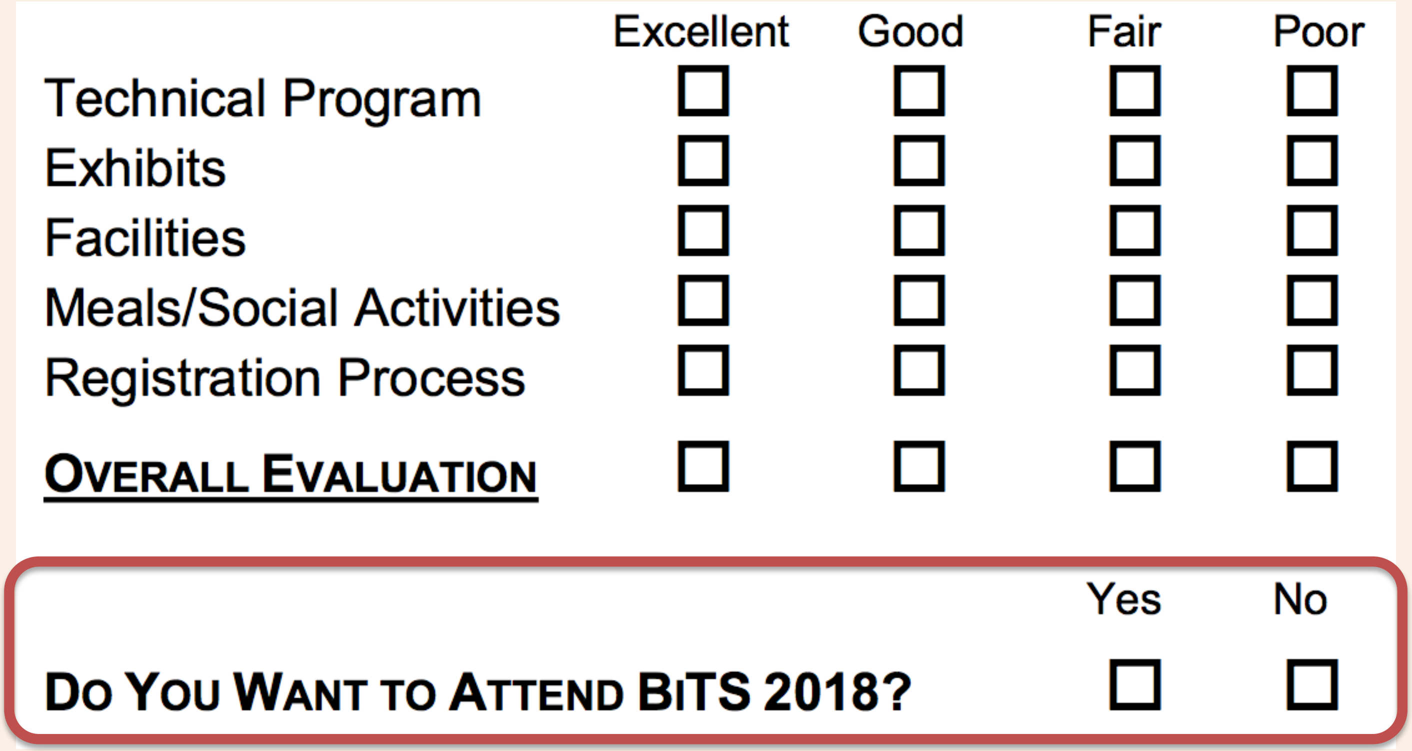

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OVERALL EVALUATION	☐	☐	☐	☐

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